

DCR1910F14

Phase Control Thyristor

Replaces DS6020-1 DS6020-2 June 2019 (LN38839)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

| Part and Ordering Number | Repetitive Peak Voltages V _{DRM} and V _{RRM} V | Conditions |
|--|---|--|
| DCR1910F14 DCR1910F12 DCR1910F10 DCR1910F08 DCR1910F06 | 1400 1200 1000 800 600 | $\begin{split} T_{vj} &= \text{-}40^{\circ}\text{C to 125}^{\circ}\text{C}, \\ I_{DRM} &= I_{RRM} = 150\text{mA}, \\ V_{DRM}, V_{RRM} t_p &= 10\text{ms}, \\ V_{DSM} \& V_{RSM} &= \\ V_{DRM} \& V_{RRM} + 100V \\ respectively \end{split}$ |

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR1910F14

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

| V_{DRM} | 1400 V |
|------------------|-----------|
| $I_{T(AV)}$ | 1910 A |
| I _{TSM} | 26000 A |
| dV/dt* | 1000 V/μs |
| dl/dt | 200 A/μs |
| | |

* Higher dV/dt selections available

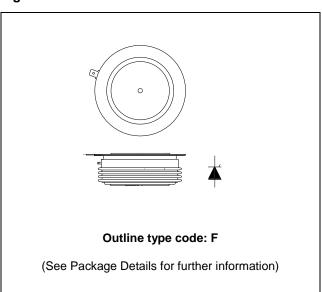


Fig. 1 Package outline

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CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

| Symbol | Parameter | Test Conditions | | Units | |
|---------------------|--------------------------------------|--------------------------|------|-------|--|
| Double Si | Double Side Cooled | | | | |
| I _{T(AV)} | Mean on-state current | Half wave resistive load | 1910 | А | |
| I _{T(RMS)} | RMS value | - | 3000 | Α | |
| I _T | Continuous (direct) on-state current | - | 2700 | А | |

SURGE RATINGS

| Symbol | Parameter | Test Conditions | Max. | Units |
|------------------|---|-------------------------------------|------|-------------------|
| I _{TSM} | Surge (non-repetitive) on-state current | 10ms half sine, $T_{case} = 125$ °C | 26.0 | kA |
| l ² t | I ² t for fusing | $V_R = 0$ | 3.38 | MA ² s |

THERMAL AND MECHANICAL RATINGS

| Symbol | Parameter | Test Conditions | | Min. | Max. | Units |
|----------------------|---------------------------------------|---|----|------|-------|-------|
| R _{th(j-c)} | Thermal resistance – junction to case | Double side cooled | DC | - | 0.02 | °C/W |
| R _{th(c-h)} | Thermal resistance – case to heatsink | Double side cooled | DC | - | 0.005 | °C/W |
| T _{vj} | Virtual junction temperature | Blocking V _{DRM} / _{VRRM} | | - | 125 | °C |
| T _{stg} | Storage temperature range | | | -40 | 140 | °C |
| F _m | Clamping force | | | 18 | 26 | kN |

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DYNAMIC CHARACTERISTICS

| Symbol | Parameter | Test Conditions | | Min. | Max. | Units |
|------------------------------------|---|---|-----------------|------|------|-------|
| I _{RRM} /I _{DRM} | Peak reverse and off-state current | At V _{RRM} /V _{DRM} , T _{case} = 125°C | | - | 150 | mA |
| dV/dt | Max. linear rate of rise of off-state voltage | To 67% V _{DRM} , T _j = 125°C, gate open | | 1000 | - | V/µs |
| dl/dt | Rate of rise of on-state current | From 67% V _{DRM} to 2000A | Repetitive 50Hz | - | 200 | A/µs |
| | | Gate source 30V, 10Ω, | Non-repetitive | - | 1000 | A/µs |
| | | $t_r < 0.5 \mu s, T_j = 125 ^{\circ} C$ | | | | |
| V_{T} | On-state voltage | I _T = 1500A, T _{case} = 125°C | | | 1.10 | V |
| $V_{T(TO)}$ | Threshold voltage | T _{case} = 125°C | | - | 0.86 | V |
| r _T | On-state slope resistance | T _{case} = 125°C | | - | 0.16 | mΩ |
| t _{gd} | Delay time | $V_D = 67\% V_{DRM}$, gate source 30V, 10Ω | | - | 3.0 | μs |
| | | $t_r = 0.5 \mu s, T_j = 25^{\circ}C$ | | | | |
| tq | Turn-off time | $T_j = 125$ °C, $V_R = 100$ V, $dI/dt = 10$ A/ μ s, | | - | 200 | μs |
| | | $dV_{DR}/dt = 20V/\mu s$ linear to 67% V_{DRM} | | | | |
| Q_S | Stored charge | $I_T = 2000A$, $tp = 1000us$, $T_j = 125$ °C, $dI/dt = 10A/\mu s$, | | - | 2000 | μC |
| I _{RR} | Reverse recovery current | | | - | 140 | Α |
| lι | Latching current | T _j = 25°C, | | - | 1 | Α |
| I _H | Holding current | T _j = 25°C, | | - | 200 | mA |

GATE TRIGGER CHARACTERISTICS AND RATINGS

| Symbol | Parameter | Test Conditions | Max. | Units |
|-----------------|--------------------------|---|------|-------|
| V_{GT} | Gate trigger voltage | V _{DRM} = 5V, T _{case} = 25°C | 3 | V |
| V_{GD} | Gate non-trigger voltage | At 40% V _{DRM} , T _{case} = 125°C | 0.3 | V |
| I _{GT} | Gate trigger current | V _{DRM} = 5V, T _{case} = 25°C | 300 | mA |
| I _{GD} | Gate non-trigger current | At 40% V _{DRM} , T _{case} = 125°C | 20 | mA |

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CURVES

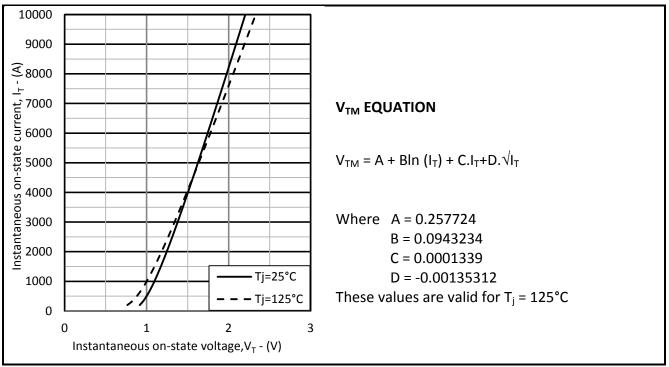


Fig.2 Maximum &minimum on-state characteristics

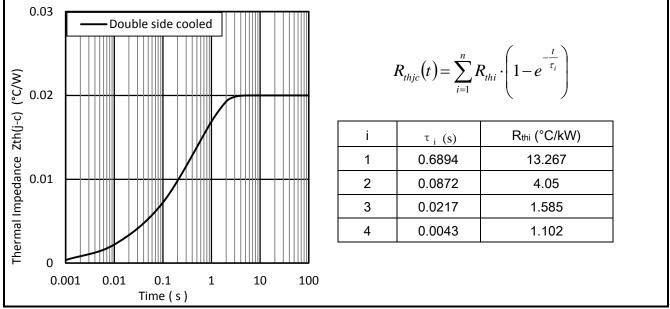


Fig.3 Maximum (limit) transient thermal impedance - junction to case (°C/W)

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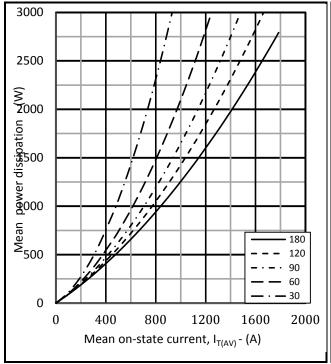


Fig.4 On-state power dissipation - sine wave

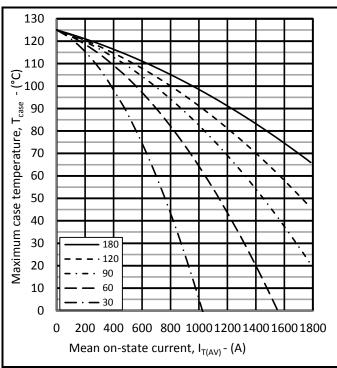


Fig.5 Maximum permissible case temperature, double side cooled – sine wave

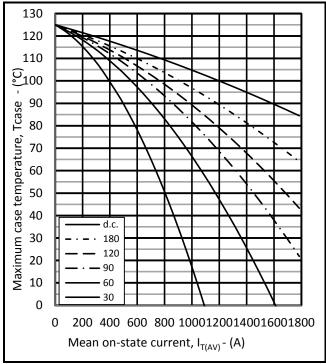


Fig.6 Maximum permissible case temperature, double side cooled – rectangular wave

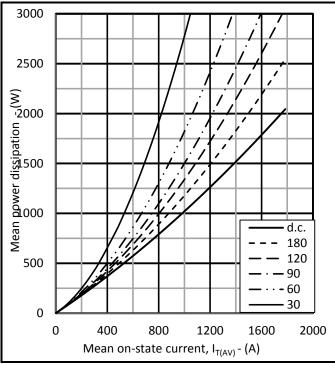
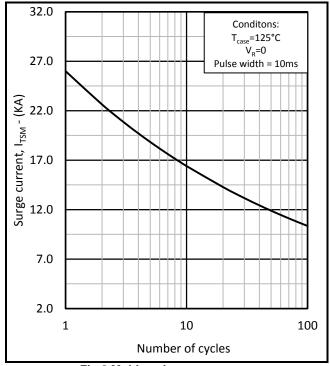
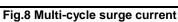


Fig.7 On-state power dissipation - rectangular wave

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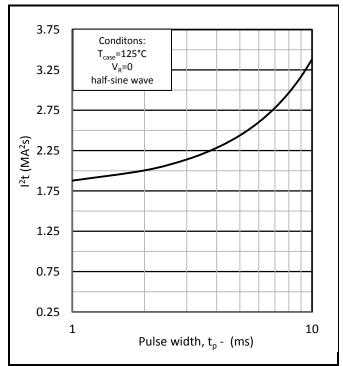


Fig.9 Single-cycle I2t

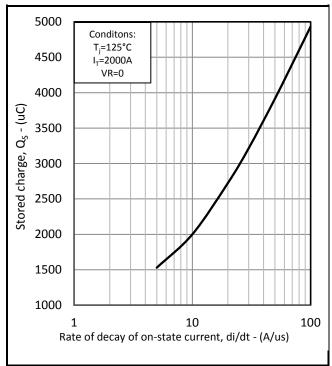


Fig.10 Stored charge vs di/dt

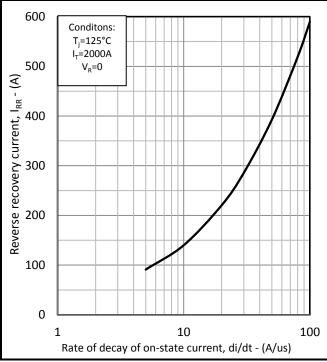


Fig.11 Reverse recovery current vs di/dt

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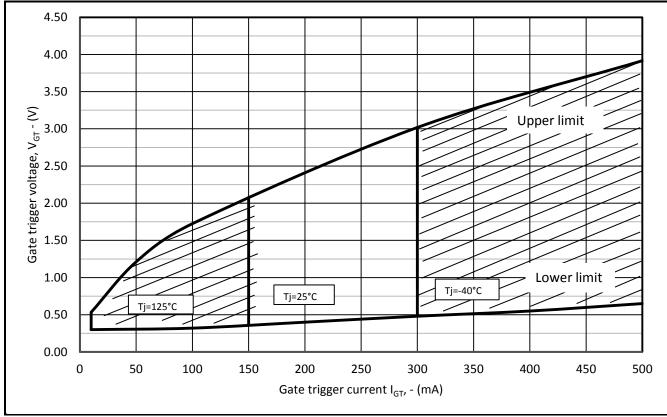


Fig.12 Gate characteristics

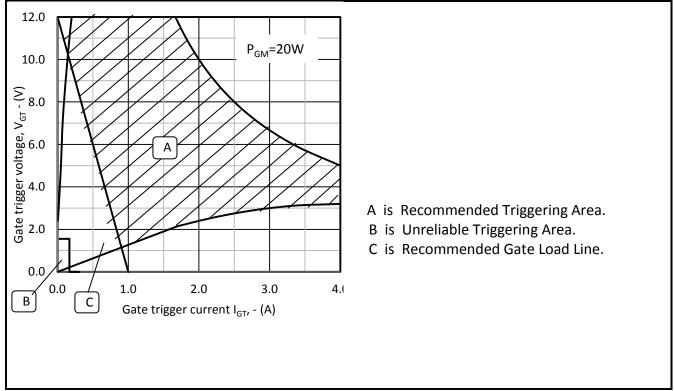


Fig.13 Gate characteristics

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PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

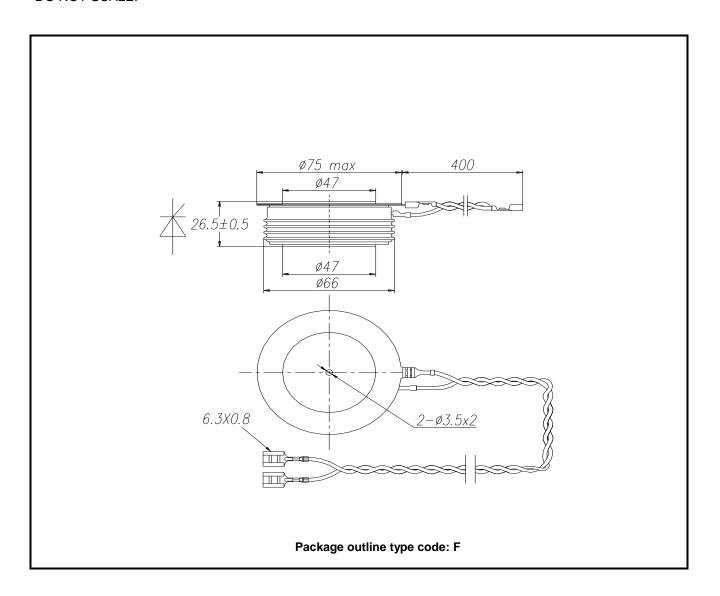


Fig.14 Package outline

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HEADQUARTERS OPERATIONS

DYNEX SEMICONDUCTOR LIMITED Doddington Road, Lincoln, Lincolnshire, LN6 3LF United Kingdom.

Phone: +44 (0) 1522 500500
Web: http://www.dynexsemi.com

CUSTOMER SERVICE

Phone: +44 (0) 1522 502753 / 502901 e-mail: powersolutions@dynexsemi.com

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